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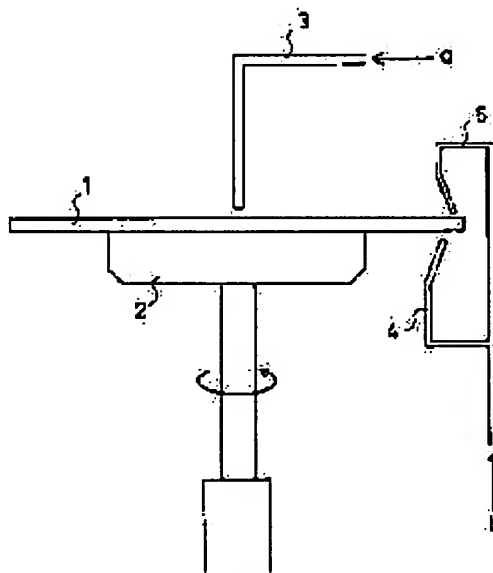
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(54) FILM SOLVENT APPLICATION DEVICE

(57)Abstract:

PURPOSE: To prevent the occurrence of the particles after baking process and improve the quality of the chip made in a semiconductor substrate by preventing the swelling of the film solvent at the surface margin of a semiconductor substrate.

CONSTITUTION: A surface cleaning nozzle 5, which jets out cleaning liquid to the surface margin of a semiconductor substrate 1, is provided being branched off from a rear cleaning nozzle 4.



LEGAL STATUS

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